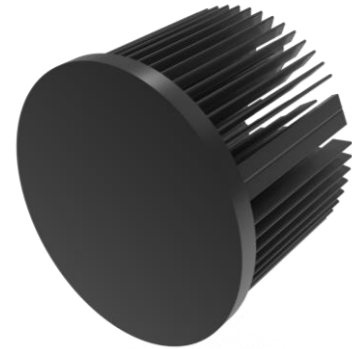


xLED

xLED-130100 Pin Fin LED Heat Sink Φ 130mm

Features VS Benefits

- * Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
 - * For spotlight and downlight designs from 4,000 to 10,000 lumen.
 - * Thermal resistance range R_{th} 0.77°C/W.
 - * Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COBs.
 - * Diameter 130.0mm - Standard height 100.0mm , Other heights on request.
 - * Forged from highly conductive aluminum.
- 2 standard colors - clear anodized - black anodized.
- Zhaga Book 3 Spot Light Modules: Bridgelux ,Cree ,Citizen ,Edison ,GE lighting, LG Innotek ,Lumileds ,Lumens ,Luminus ,Nichia ,Osram ,Philips ,Prolight Opto, Samsung ,Seoul ,Tridonic ,Vossloh-Schwabe ,Xicato.



- 01) Bridelux: Vero 18/22 Vero SE 18/29 LED engines;
- 02) Cree: XLamp CXA 25xx, Xlamp CXB 25xx, CXA 30xx, Xlamp CXB 30xx LED engi
- 03) Citizen: CLU036, CLU038, CLU721, CLU711, CLU046, CLU048, CLU731 LED engines;
- 04) Edison: EdiLex III COB LED engines;
- 05) GE lighting: Infusion™ LED engines;
- 06) LG Innotek: 32W, 42W, 56W LED engines;
- 07) LumiLEDs: LUXEON 1211, LUXEON 1216, LUXEON 1812, LUXEON 1825 LED engi
- 08) Lumens: Ergon-COB-2530, 2540, 3050, 3070 LED engines;
- 09) Luminus: CXM-18, CLM-22, CXM-22 LED engines;
- 10) Nichia: NFCWL036B, NFCLL036B, NFCWL060B, NFCLL060B LED engines;
- 11) Osram: SOLERIQ® S 19, Core series LED engines;
- 12) Philips: Fortimo SLM LED engines;
- 16) Prolight Opto: PABS, PABA, PACB, PANA LED engines;
- 13) Samsung: LC026B, LC033B, LC040B, LC040D, LC060D, LC080D LED engines;
- 14) Seoul Semiconductor: Acrich MJT COBs, DC COB LED engines;
- 15) Tridonic: SLE G6 19mm, SLE G6 23mm LED engines;
- 17) Vossloh-Schwabe: LUGA Shop and LUGA C LED engines;
- 18) Xicato: XSM, XIM,XTM LED engines;

Order Information

Example:xLED-130100-B

Example:xLED-130100 - **1**

- 1** Anodising Color
- B-Black
- C-Clear
- Z-Custom

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.



xLED

xLED-130100 Pin Fin LED Heat Sink Φ130mm

The thermal data table

	Model No.	xLED-130100
	Heatsink Size	Φ130xH100mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	958.0
	Dissipated power (T _{hs-amb} ,50°C)	65.0 (W)
	Cooling surface area (mm ²)	357538
	Thermal Resistance (R _{hs-amb})	0.77 (°C/W)

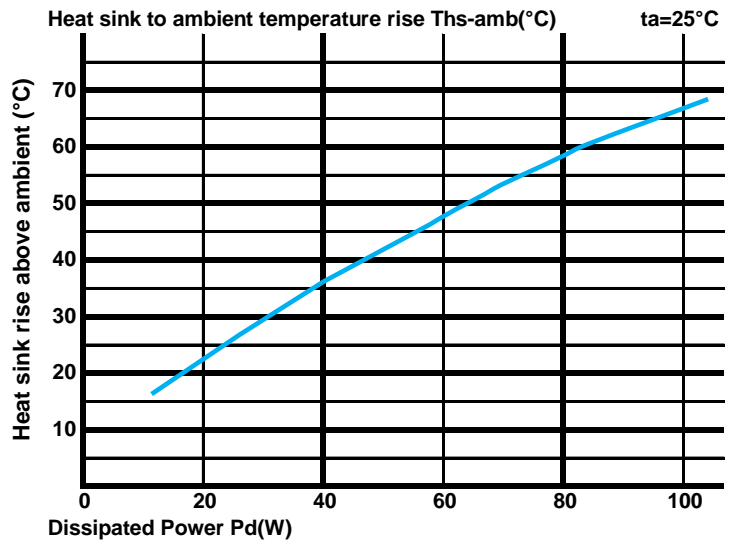
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

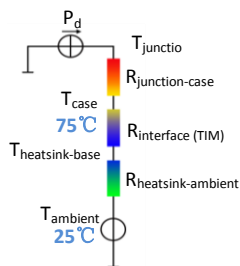
Dissipated Power Pd(W)	Pd = Pe x (1-ηL)	Heat sink to ambient thermal resistance R _{hs-amb} (°C/W)	Heat sink to ambient temperature rise T _{hs-amb} (°C)
		xLED-130100	
20.0		1.10	22.0
40.0		0.90	36.0
60.0		0.78	47.0
80.0		0.73	58.0
100.0		0.66	66.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W] ; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R_{junction-case}, the thermal resistance of the TIM outside the package is R_{interface (TIM)} [°C/W], the thermal resistance with the heat sink is R_{thermal-sink-ambient} [°C/W], and the ambient temperature is T_{ambient} [°C].

*Thermal resistances outside the package R_{interface (TIM)} and R_{thermal-sink-ambient} can be integrated into the thermal resistance R_{case-ambient} at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot P_d + T_{ambient}$$